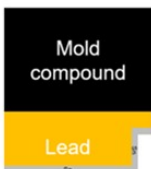
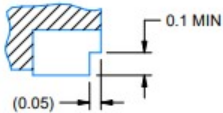
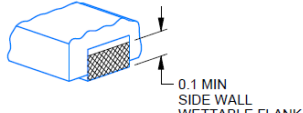


|                                                                                 |                      |                                            |                   |
|---------------------------------------------------------------------------------|----------------------|--------------------------------------------|-------------------|
| <b>PCN Number:</b>                                                              | <b>20260826003.2</b> | <b>PCN Issued</b>                          | August 26, 2026   |
| Qualification of TI CDAT as an additional Assembly/Test site for select devices |                      | <b>Sample request deadline:</b>            | October 25, 2026  |
|                                                                                 |                      | <b>Estimated 1<sup>st</sup> ship date:</b> | February 22, 2027 |
| <b>*Sample requests received after October 25, 2026* will not be supported.</b> |                      |                                            |                   |

|                       |                                                                              |
|-----------------------|------------------------------------------------------------------------------|
| <b>Change Type(s)</b> | Assembly Site<br>Assembly Material<br>Packing/Shipping/Labeling<br>Test Site |
| <b>ZVEI ID</b>        | SEM-PA-14, SEM-PA-18, SEM-PW-03, SEM-TF-01                                   |

### PCN Details

| <b>Description of Change:</b>                                                                                                                                                                  |                                                                                                                                               |                                                                                                                                                    |
|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------|
| Texas Instruments Incorporated is announcing the qualification of TI CDAT as an additional Assembly/Test site for the devices listed below. Material differences between sites are as follows. |                                                                                                                                               |                                                                                                                                                    |
|                                                                                                                                                                                                | <b>Current Site</b>                                                                                                                           | <b>Additional Site</b>                                                                                                                             |
| Assembly/Test site                                                                                                                                                                             | UTL1/UTL2                                                                                                                                     | TI CDAT                                                                                                                                            |
| Final wafer thickness                                                                                                                                                                          | 15mils                                                                                                                                        | 10.5mils                                                                                                                                           |
| Processing technology                                                                                                                                                                          |  <p>Step-cut singulated wettable flank with Sn plating</p> |  <p>Through-cut singulated wettable flank with Sn plating</p> |
| Lead Sidewall Outline                                                                                                                                                                          |                                                            |                                                               |
| Qual details are provided in the Qual Data Section.<br>Test coverage, insertions, conditions will remain consistent with current testing.                                                      |                                                                                                                                               |                                                                                                                                                    |
| <b>Reason for Change:</b>                                                                                                                                                                      | Continuity of supply                                                                                                                          |                                                                                                                                                    |

|                                                                           |                                                                                                                        |
|---------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------|
| <b>Anticipated impact on Form, Fit, Function, Quality or Reliability:</b> | Physical aspects of the device have changed. Request the Supporting Data Packet (SDP) for more details on the changes. |
| <b>Impact on Environmental</b>                                            | Checked boxes indicate the status of environmental ratings                                                             |

| <b>Ratings</b>                                                    | following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.                                                                                                                                                                                                                  |                                               |                                               |               |           |                                               |                                               |                                               |                                               |  |  |
|-------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|-----------------------------------------------|---------------|-----------|-----------------------------------------------|-----------------------------------------------|-----------------------------------------------|-----------------------------------------------|--|--|
|                                                                   | <table border="1"> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </table> | RoHS                                          | REACH                                         | Green Status  | IEC 62474 | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change |  |  |
| RoHS                                                              | REACH                                                                                                                                                                                                                                                                                                                                               | Green Status                                  | IEC 62474                                     |               |           |                                               |                                               |                                               |                                               |  |  |
| <input checked="" type="checkbox"/> No Change                     | <input checked="" type="checkbox"/> No Change                                                                                                                                                                                                                                                                                                       | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change |               |           |                                               |                                               |                                               |                                               |  |  |
| <b>Changes to product identification resulting from this PCN:</b> | <b>Assembly Site Information</b>                                                                                                                                                                                                                                                                                                                    |                                               |                                               |               |           |                                               |                                               |                                               |                                               |  |  |
|                                                                   | Assembly Site                                                                                                                                                                                                                                                                                                                                       | Assembly Site Origin (22L)                    | Assembly Country Code (23L)                   | Assembly City |           |                                               |                                               |                                               |                                               |  |  |
|                                                                   | UTL1                                                                                                                                                                                                                                                                                                                                                | NSE                                           | THA                                           | Bangkok       |           |                                               |                                               |                                               |                                               |  |  |
|                                                                   | CDAT                                                                                                                                                                                                                                                                                                                                                | CDA                                           | CHN                                           | Chengdu       |           |                                               |                                               |                                               |                                               |  |  |
| Sample product shipping label (not actual product label):         |                                                                                                                                                                                                                                                                                                                                                     |                                               |                                               |               |           |                                               |                                               |                                               |                                               |  |  |
|                                                                   |                                                                                                                                                                                                                                                                                                                                                     |                                               |                                               |               |           |                                               |                                               |                                               |                                               |  |  |

| Products Affected: |                    |                    |  |
|--------------------|--------------------|--------------------|--|
| LMR36503MSAERPERQ1 | LMR36506MSC3RPERQ1 | LMR43610MSC5RPERQ1 |  |
| LMR36503MSC3RPERQ1 | LMR36506MSC5RPERQ1 | LMR43610RS3QRPERQ1 |  |
| LMR36503MSC5RPERQ1 | LMR36506MSCQRPERQ1 | LMR43610RS5QRPERQ1 |  |
| LMR36503MSCERPERQ1 | LMR36506RS3QRPERQ1 | LMR43620MC3RPERQ1  |  |
| LMR36503MSCQRPERQ1 | LMR43606MSC3RPERQ1 | LMR43620MC5RPERQ1  |  |
| LMR36503RS3ERPERQ1 | LMR43606MSC5RPERQ1 | LMR43620MSC3RPERQ1 |  |
| LMR36503RS3QRPERQ1 | LMR43606RS3RPERQ1  | LMR43620MSC5RPERQ1 |  |
| LMR36503RS5QRPERQ1 | LMR43606RS5RPERQ1  | LMR43620RS3QRPERQ1 |  |
| LMR36503RSERPERQ1  | LMR43610MSC3RPERQ1 | LMR43620RS5QRPERQ1 |  |

**Qualification Report**  
**Automotive Qualification Summary**  
**(As per AEC-Q100 Rev. J and JEDEC Guidelines)**  
Approve Date 11-August-2026

**Product Attributes**

| Attributes               | Qual Device:<br><a href="#">LMR36506MSCQRPERQ1</a> | QBS Process Reference:<br><a href="#">LMR33620CQRNXTQ1</a> |
|--------------------------|----------------------------------------------------|------------------------------------------------------------|
| Automotive Grade Level   | Grade 1                                            | Grade 1                                                    |
| Operating Temp Range (C) | -40 to 125                                         | -40 to 125                                                 |
| Product Function         | Power Management                                   | Power Management                                           |
| Wafer Fab Supplier       | RFAB                                               | RFAB                                                       |
| Assembly Site            | CDAT                                               | UTL1                                                       |
| Package Group            | QFN                                                | QFN                                                        |
| Package Designator       | RPE                                                | RNX                                                        |
| Pin Count                | 9                                                  | 12                                                         |

QBS: Qual By Similarity, also known as Generic Data

Qual Device LMR36506MSCQRPERQ1 is qualified at MSL2 260C

Note 1: HTSL is not considered per AEC-Q100 Rev-J Table 3 Assembly Site Transfer

Note 2: Affected devices in PCN have justification to use Process QBS references for Group B tests based on AEC-Q100 Rev-J Appendix 1 A1.2, silicon wafer fab and die attributes were qualified.

Note 3: 1 lot of Electrical characterization is allowed per A1.5.1 Multiple Sites - When the specific product or process attribute to be qualified or requalified will affect more than one wafer fab site or assembly site, a minimum of one lot of testing per affected site is required

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

| Type                                                        | #  | Test Spec                           | Min Lot Qty | SS / Lot | Test Name                     | Condition          | Duration    | Qual Device:<br><a href="#">LMR36506MSCQRPERQ1</a> | QBS Process Reference:<br><a href="#">LMR33620CQRNXTQ1</a> |
|-------------------------------------------------------------|----|-------------------------------------|-------------|----------|-------------------------------|--------------------|-------------|----------------------------------------------------|------------------------------------------------------------|
| <b>Test Group A - Accelerated Environment Stress Tests</b>  |    |                                     |             |          |                               |                    |             |                                                    |                                                            |
| PC                                                          | A1 | JEDEC J-STD-020 JESD22-A113         | 3           | 77       | Preconditioning               | MSL2 260C          | -           | 3/693/0                                            | -                                                          |
| HAST                                                        | A2 | JEDEC JESD22-A110                   | 3           | 77       | Biased HAST                   | 130C/85%RH         | 96 Hours    | 3/231/0                                            | -                                                          |
| AC/HAST                                                     | A3 | JEDEC JESD22-A102/JEDEC JESD22-A118 | 3           | 77       | Unbiased HAST                 | 130C/85%RH         | 96 Hours    | 3/231/0                                            | -                                                          |
| TC                                                          | A4 | JEDEC JESD22-A104 and Appendix 3    | 3           | 77       | Temperature Cycle             | -55C/150C          | 1000 Cycles | 3/231/0                                            | -                                                          |
| TC                                                          | A4 | JEDEC JESD22-A104 and Appendix 3    | 3           | 77       | Temperature Cycle             | -65/150C           | 500 Cycles  | 3/231/0                                            | -                                                          |
| HTSL                                                        | A6 | JEDEC JESD22-A103                   | 1           | 45       | High Temperature Storage Life | 150C               | 1000 Hours  | Note 1                                             | -                                                          |
| <b>Test Group B - Accelerated Lifetime Simulation Tests</b> |    |                                     |             |          |                               |                    |             |                                                    |                                                            |
| HTOL                                                        | B1 | JEDEC JESD22-A108                   | 3           | 77       | Life Test                     | 125C               | 1000 Hours  | Note 2                                             | 3/231/0                                                    |
| ELFR                                                        | B2 | AEC Q100-008                        | 3           | 800      | Early Life Failure Rate       | 125C               | 48 Hours    | Note 2                                             | 3/2400/0                                                   |
| <b>Test Group C - Package Assembly Integrity Tests</b>      |    |                                     |             |          |                               |                    |             |                                                    |                                                            |
| SD                                                          | C3 | JEDEC J-STD-002                     | 1           | 15       | PB-Free Solderability         | >95% Lead Coverage | -           | 1/15/0                                             | -                                                          |
| PD                                                          | C4 | JEDEC JESD22-B100 and B108          | 3           | 10       | Physical Dimensions           | Cpk>1.67           | -           | 3/30/0                                             | -                                                          |
| <b>Test Group D - Die Fabrication Reliability Tests</b>     |    |                                     |             |          |                               |                    |             |                                                    |                                                            |
| EM                                                          | D1 | JESD61                              | -           | -        | Electromigration              | -                  | -           | Completed Per Process Technology Requirements      | Completed Per Process Technology Requirements              |

|                                                     |    |              |   |    |                                      |                              |             |                                               |                                               |
|-----------------------------------------------------|----|--------------|---|----|--------------------------------------|------------------------------|-------------|-----------------------------------------------|-----------------------------------------------|
| Tddb                                                | D2 | JESD35       | - | -  | Time Dependent Dielectric Breakdown  | -                            | -           | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| HCI                                                 | D3 | JESD60 & 28  | - | -  | Hot Carrier Injection                | -                            | -           | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| BTI                                                 | D4 | -            | - | -  | Bias Temperature Instability         | -                            | -           | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| SM                                                  | D5 | -            | - | -  | Stress Migration                     | -                            | -           | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| <b>Test Group E - Electrical Verification Tests</b> |    |              |   |    |                                      |                              |             |                                               |                                               |
| ESD                                                 | E2 | AEC Q100-002 | 1 | 3  | ESD HBM                              | -                            | 2000 Volts  | Note 1                                        | 1/3/0                                         |
| ESD                                                 | E3 | AEC Q100-011 | 1 | 3  | ESD CDM                              | -                            | 500 Volts   | Note 1                                        | 1/3/0                                         |
| LU                                                  | E4 | AEC Q100-004 | 1 | 3  | Latch-Up                             | Per AEC Q100-004             | -           | Note 1                                        | 1/6/0                                         |
| ED                                                  | E5 | AEC Q100-009 | 1 | 30 | Electrical Distributions             | Cpk>1.67 Room, hot, and cold | -           | 1/30/0 Note 3                                 | 3/90/0                                        |
| <b>Additional Tests</b>                             |    |              |   |    |                                      |                              |             |                                               |                                               |
| BLR                                                 | T1 | -            | - | -  | Board Level Reliability - Temp Cycle | -40/125C                     | 1000 Cycles | 1/48/0                                        | -                                             |

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

#### **Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

#### **E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2302-057

# Qualification Report

## Automotive Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 22-May-2024

### Product Attributes

| Attributes                    | Qual Device in UTL1<br><a href="#">LMR36503MSCERPERQ1</a> | QBS Process Reference: ELFR<br><a href="#">TPS7B8250EPWPRQ1</a> | Qual device in CDAT :<br><a href="#">LMR36503MSCERPERQ1</a> |
|-------------------------------|-----------------------------------------------------------|-----------------------------------------------------------------|-------------------------------------------------------------|
| Automotive Grade Level        | Grade 0                                                   | Grade 0                                                         | Grade 0                                                     |
| Operating Temp Range (C)      | -40 to 150                                                | -40 to 150                                                      | -40 to 150                                                  |
| Product Function              | Power Management                                          | Power Management                                                | Power Management                                            |
| <b>Die Attributes</b>         |                                                           |                                                                 |                                                             |
| Wafer Fab Supplier            | RFAB                                                      | RFAB                                                            | RFAB                                                        |
| Wafer Process                 | LBC9                                                      | LBC9                                                            | LBC9                                                        |
| Die Size (L,W) (um)           | 1500 x 1500                                               | 980 x 1280                                                      | 1500 x 1500                                                 |
| <b>Package Attributes</b>     |                                                           |                                                                 |                                                             |
| Assembly Site                 | UTL1                                                      | MLA                                                             | CDAT                                                        |
| Package Group                 | QFN                                                       | TSSOP                                                           | QFN                                                         |
| Package Designator            | RPE                                                       | PWP                                                             | RPE                                                         |
| Package Size (mm)             | 2 x 2                                                     | 5 x 4.4                                                         | 2 x 2                                                       |
| Body Thickness (mm)           | 0.9                                                       | 1                                                               | 0.9                                                         |
| Pin Count                     | 9                                                         | 14                                                              | 9                                                           |
| Lead Finish                   | MATTE SN                                                  | NIPDAU                                                          | MATTE SN                                                    |
| Lead Pitch(mm)                | 0.5                                                       | 0.65                                                            | 0.5                                                         |
| Mold Compound Supplier        | SUMITOMO                                                  | SUMITOMO                                                        | SUMITOMO                                                    |
| Mold Compound Supplier Number | EME-G700LTD                                               | EME-G700LB                                                      | EME-G700LTD                                                 |

QBS: Qual By Similarity

Qual Device LMR36503MSCERPERQ1 is qualified at MSL2 260C

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type                                                       | #  | Test Spec                           | Min Lot Qty | SS / Lot | Test Name                     | Condition   | Duration    | Qual Device in UTL1<br><a href="#">LMR36503MSCERPERQ1</a> | QBS Process Reference: ELFR<br><a href="#">TPS7B8250EPWPRQ1</a> | Qual device in CDAT :<br><a href="#">LMR36503MSCERPERQ1</a> |
|------------------------------------------------------------|----|-------------------------------------|-------------|----------|-------------------------------|-------------|-------------|-----------------------------------------------------------|-----------------------------------------------------------------|-------------------------------------------------------------|
| <b>Test Group A - Accelerated Environment Stress Tests</b> |    |                                     |             |          |                               |             |             |                                                           |                                                                 |                                                             |
| PC                                                         | A1 | JEDEC J-STD-020 JESD22-A113         | 3           | 77       | Preconditioning               | MSL2 260C   | -           | 3/231/0                                                   |                                                                 | 3/693/0                                                     |
| HAST                                                       | A2 | JEDEC JESD22-A110                   | 3           | 77       | Biased HAST                   | 110C/85%RH  | 264 Hours   | 3/231/0                                                   |                                                                 | -                                                           |
| HAST                                                       | A2 | JEDEC JESD22-A110                   | 3           | 77       | Biased HAST                   | 130C/85%RH  | 96 Hours    | -                                                         |                                                                 | 3/231/0                                                     |
| AC/UHAST                                                   | A3 | JEDEC JESD22-A102/JEDEC JESD22-A118 | 3           | 77       | Autoclave                     | 121C/15psig | 96 Hours    | 3/231/0                                                   |                                                                 | -                                                           |
| AC/UHAST                                                   | A3 | JEDEC JESD22-A102/JEDEC JESD22-A118 | 3           | 77       | Unbiased HAST                 | 130C/85%RH  | 96 Hours    | -                                                         |                                                                 | 3/231/0                                                     |
| TC                                                         | A4 | JEDEC JESD22-A104 and Appendix 3    | 3           | 77       | Temperature Cycle             | -55C/150C   | 1500 Cycles | 3/231/0                                                   |                                                                 | 3/231/0                                                     |
| PTC                                                        | A5 | JEDEC JESD22-A105                   | 1           | 45       | PTC                           | -40/150C    | 1000 Cycles | Not applicable                                            |                                                                 | -                                                           |
| HTSL                                                       | A6 | JEDEC JESD22-A103                   | 1           | 45       | High Temperature Storage Life | 175C        | 1000 Hours  | 1/45/0                                                    |                                                                 | 1/45/0                                                      |

| Test Group B - Accelerated Lifetime Simulation Tests |    |                            |   |     |                                     |                                            |            |                                               |                                               |                                               |
|------------------------------------------------------|----|----------------------------|---|-----|-------------------------------------|--------------------------------------------|------------|-----------------------------------------------|-----------------------------------------------|-----------------------------------------------|
| HTOL                                                 | B1 | JEDEC JESD22-A108          | 3 | 77  | Life Test                           | 150C                                       | 1000 Hours | QBS to CDAT package device                    |                                               | 3/231/0                                       |
| ELFR                                                 | B2 | AEC Q100-008               | 3 | 800 | Early Life Failure Rate             | 150C                                       | 48 Hours   | -                                             | 3/2400/0                                      | -                                             |
| Test Group C - Package Assembly Integrity Tests      |    |                            |   |     |                                     |                                            |            |                                               |                                               |                                               |
| WBS                                                  | C1 | AEC Q100-001               | 1 | 30  | Wire Bond Shear                     | Minimum of 5 devices, 30 wires<br>Cpk>1.67 | Wires      | Not applicable                                |                                               | Not applicable                                |
| WBP                                                  | C2 | MIL-STD883 Method 2011     | 1 | 30  | Wire Bond Pull                      | Minimum of 5 devices, 30 wires<br>Cpk>1.67 | Wires      | Not applicable                                |                                               | Not applicable                                |
| SD                                                   | C3 | JEDEC J-STD-002            | 1 | 15  | PB-Free Solderability               | >95% Lead Coverage                         | -          | 1/15/0                                        |                                               | 1/15/0                                        |
| PD                                                   | C4 | JEDEC JESD22-B100 and B108 | 3 | 10  | Physical Dimensions                 | Cpk>1.67                                   | -          | -3/30/0                                       |                                               | 3/30/0                                        |
| Test Group D - Die Fabrication Reliability Tests     |    |                            |   |     |                                     |                                            |            |                                               |                                               |                                               |
| EM                                                   | D1 | JESD61                     | - | -   | Electromigration                    | -                                          | -          | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| TDDb                                                 | D2 | JESD35                     | - | -   | Time Dependent Dielectric Breakdown | -                                          | -          | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| HCI                                                  | D3 | JESD60 & 28                | - | -   | Hot Carrier Injection               | -                                          | -          | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| BTI                                                  | D4 | -                          | - | -   | Bias Temperature Instability        | -                                          | -          | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| SM                                                   | D5 | -                          | - | -   | Stress Migration                    | -                                          | -          | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements | Completed Per Process Technology Requirements |
| Test Group E - Electrical Verification Tests         |    |                            |   |     |                                     |                                            |            |                                               |                                               |                                               |
| ESD                                                  | E2 | AEC Q100-002               | 1 | 3   | ESD HBM                             | -                                          | 4000 Volts | Device specific data taken on CDAT package    |                                               | 1/3/0                                         |
| ESD                                                  | E3 | AEC Q100-011               | 1 | 3   | ESD CDM                             | -                                          | 1500 Volts | Device specific data taken on CDAT package    |                                               | 1/3/0                                         |
| LU                                                   | E4 | AEC Q100-004               | 1 | 3   | Latch-Up                            | Per AEC Q100-004                           | 150C       | Device specific data taken on CDAT package    |                                               | 1/3/0                                         |
| ED                                                   | E5 | AEC Q100-009               | 3 | 30  | Electrical Distributions            | Cpk>1.67<br>Room, hot, and cold            | -          | Device specific data taken on CDAT package    |                                               | 3/90/0                                        |

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

#### Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

#### E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2312-066

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification

by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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